Texas Instruments

Bill of Materials

TI DESIGNS TIDA-00274

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part Number	Note
1	1	C1	CAP ALUM 100UF 63V 20% RADIAL	PANASONIC	ECA-1JHG101	P5582-ND	
2	1	C2	CAP ALUM 10UF 63V 20% RADIAL	PANASONIC	ECA-1JM100	P5189-ND	
3	5	C3,C4,C5,C8,C25	CAP SMD0805 CERM 0.1UFD 100V 10% X7R ROHS	TDK	C2012X7R2A104K	445-1418-1	
4	4	C6,C9,C15,C21	CAP CER 0.47UF 16V 10% X7R 0805	TDK	C2012X7R1C474K	445-1357-1-ND	
5	0	C13,C14,C16	CAP CER 0.47UF 16V 10% X7R 0806	TDK	C2012X7R1C474K	445-1357-1-ND	Do not assemble
6	1	C7	CAP CER 10000PF 100V X7R 0805	TDK	C2012X7R2A103M	445-1344-1-ND	
7	1	C10	CAP CER 1000PF 50V 10% X7R 0805	TDK	C2012X7R1H102K	445-1347-1-ND	
8	5	C11,C12,C22,C23,C24	CAP CER 100PF 50V 5% NP0 0805	TDK	C2012C0G1H101J	445-1329-1-ND	
9	3	C17,C18,C19	CAP CER 0.1UF 16V 10% X7R 0805	MURATA	GRM219R71C104KA01D	490-1683-1-ND	
10	3	C26,C27,C28	CAP CER 10UF 10V 20% X7R 0805	TDK	C2012X7R1A106M	445-7592-1-ND	
11	0	C20	CAP CER 2200PF 25V 10% X7R 0805	Kemet	C0805C222K3RACTU	399-9201-1-ND	Do not assemble
12	7	R1,R2,R6,R16,R17,R18,R19	RES 4.99K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF4991V	P4.99KCCT-ND	
13	1	R3	RES 33 OHM 1/8W 5% 0805 SMD	PANASONIC	ERJ-6GEYJ330V	P33ACT-ND	
14	1	R4	RES 402K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF4023V	P402KCCT-ND	
15	4	R12,R13,R14,R15	RES 95.3K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF9532V	P95.3KCCT-ND	
16	9	R25,R26,R27,R29,R30, R31,R32,R33,R34	RES 0.0 OHM (jumpers) 1/8W 0805 SMD	PANASONIC	ERJ-6GEY0R00V	P0.0ACT-ND	
17	1	R24	RES 12K OHM 1/8W 5% 0805 SMD	PANASONIC	ERJ-6GEYJ123V	P12KACT-ND	
18	3	R20,R21,R22	RES 10K OHM 1/8W 5% 0805 SMD	PANASONIC	ERJ-6GEYJ103V	P10KACT-ND	
19	1	R8	RESISTOR SMD1206 0.01 OHMS 1% 1W ROHS	VISHAY	WSLP1206R0100FEA	WSLP-.01CT	
20	2	R7,R9	RES 1.00K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF1001V	P1.00KCCT-ND	
21	1	R10	RES 33.2K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF3322V	P33.2KCCT-ND	
22	2	R5,R11	RES 66.5K OHM 1/8W 1% 0805 SMD	PANASONIC	ERJ-6ENF6652V	P66.5KCCT-ND	
23	1	R35	RES 100K OHM 1/8W 5% 0805 SMD	PANASONIC	ERJ-6GEYJ104V	P100KACT-ND	
24	1	R28	TRIMMER 10K OHM 0.5W	Bourns	3386P-1-103LF	3386P-103LF-ND	
25	1	R23	RES 47K OHM 1/8W 5% 0805	Samsung	RC2012J473CS	1276-5568-1-ND	Do not assemable
26	1	L1	FERRITE 1.5A 40 OHM 0805 SMD	Laird-Signal	MI0805K400R-10	240-2389-1-ND	
27	1	J1	CONN HEADER .100 SINGL STR 16POS	SULLINS	PBC16SAAN	S1011E-16-ND	
28	1	J2	TERMINAL BLOCK 5.08MM VERT 2POS	ON SHORE TECHNOLOGY	ED120/2DS	ED1609-ND	
29	1	J3	TERMINAL BLOCK 5.08MM VERT 3POS	ON SHORE TECHNOLOGY	ED120/3DS	ED1610-ND	
30	1	J4	CONN HEADER .100 SINGL STR 4POS	SULLINS	PBC04SAAN	S1011E-04-ND	
31	1	J6	CONN RCPT MICRO USB TYPE AB	TE Connectivity	1981584-1	A97799CT-ND	
32	1	J7	HEADER THRU MALE 1X5 100LS GOLD ROHS	SULLINS	PBC05SAAN	S1011E-05	
33	1	JP1	CONN HEADER .100 SINGL STR 3POS	SULLINS	PBC03SAAN	S1011E-03-ND	
34	1	JP2	CONN HEADER .100 SINGL STR 2POS	SULLINS	PBC02SAAN	S1011E-02-ND	
35	1	S1	SWITCH TACTILE SPST-NO 0.05A 12V	TE Connectivity	FSM4JH	450-1650-ND	
36	6	TP9,TP10,TP14,TP15,TP16,TP17	TEST POINT PC COMPACT .063"D BLK	Keystone Electronics	5006	5006K-ND	
37	11	TP1,TP2,TP3,TP4,TP5,TP6,TP7,TP8,TP11,TP12,TP13	TEST POINT PC COMPACT .063"D ORN	Keystone Electronics	5008	5008K-ND	
38	1	U4	IC USB FS SERIAL UART 28-SSOP	FTDI	FT232RL-REEL	768-1007-1-ND	
39	1	U1	MOTOR DRIVE POWER AMP HTSSOP44-DDW ROHS	TEXAS INSTRUMENTS	DRV8313PWPR	DRV8313PWPR	
41	1	U2	OPAMP LOW DISTORTION 50MHz HI CMRR RRI/O SOT23-DBV ROHS	TEXAS INSTRUMENTS	OPA365AIDBVR	296-20645-1	
42	1	U3	IC VOLT SUPERVISOR 2.93V SOT23-3	TEXAS INSTRUMENTS	TLV809K33DBZT	296-28210-1	

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43	1	U5	IC MCU 16BIT 16KB FLASH 28TSSOP	TEXAS INSTRUMENTS	MSP430G2553IPW28R	MSP430G2433IPW28R	
44	1	U6	IC REG LDO 50MA 5.0V 8-SOIC	TEXAS INSTRUMENTS	LM2936HVMAX-5.0	LM2936HVMAX-5.0CT	
45	1	U7	IC REG LDO 3.3V .15A SOT23-5	TEXAS INSTRUMENTS	TLV70433DBVT	296-27946-2-ND	

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